

# **IC PACKAGE WITH AN IMPLANTED HEAT-DISSIPATION FIN**

## **ABSTRACT**

An IC package with an implanted heat-dissipation fin is introduced. The IC package provides a plastic package to seal an IC chip. One end of the heat-dissipation fin is implanted inside the plastic package, and another end is left outside for directly heat-exchanging with a surrounding heat-transfer media. By providing the implanted heat-dissipation fin, a more efficient and broader heat-dissipation path for the IC package can be established so that the total heat dissipation of the IC package can be enhanced.